IXYS

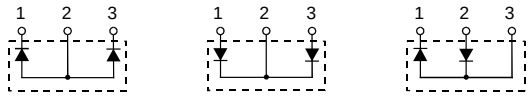
Fast Recovery Epitaxial Diode (FRED) Module

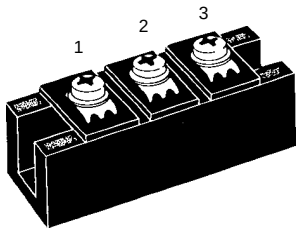
MEA 300-06 DA
MEK 300-06 DA
MEE 300-06 DA

V_{RRM} = 600 V
I_{FAVM} = 304 A
t_{rr} = 250 ns

Preliminary data

V_{RSM} V	V_{RRM} V	Type
600	600	MEA 300-06DA
		MEK 300-06DA
		MEE 300-06DA





Symbol	Test Conditions	Maximum Ratings	
I_{FRMS}	T_C = 75 °C	430	A
I_{FAVM} ①	T_C = 75 °C; rectangular, d = 0.5	304	A
I_{FRM}	t_P < 10 µs; rep. rating, pulse width limited by T_{VJM}	1640	A
I_{FSM}	T_{VJ} = 45°C; t = 10 ms (50 Hz), sine	2400	A
	t = 8.3 ms (60 Hz), sine	2640	A
	T_{VJ} = 150°C; t = 10 ms (50 Hz), sine	2160	A
	t = 8.3 ms (60 Hz), sine	2380	A
I^2t	T_{VJ} = 45°C; t = 10 ms (50 Hz), sine	28800	A^2s
	t = 8.3 ms (60 Hz), sine	29300	A^2s
	T_{VJ} = 150°C; t = 10 ms (50 Hz), sine	23300	A^2s
	t = 8.3 ms (60 Hz), sine	23800	A^2s
T_{VJ}		-40...+150	°C
T_{stg}		-40...+125	°C
T_{Smax}		110	°C
P_{tot}	T_C = 25°C	875	W
V_{ISOL}	50/60 Hz, RMS t = 1 min	3000	V~
	I_{ISOL} ≤ 1 mA t = 1 s	3600	V~
M_d	Mounting torque (M6)	2.25-2.75/20-25	Nm/lb.in.
	Terminal connection torque (M6)	4.50-5.50/40-48	Nm/lb.in.
d_S	Creeping distance on surface	12.7	mm
d_A	Strike distance through air	9.6	mm
a	Maximum allowable acceleration	50	m/s^2
Weight		150	g

Symbol	Test Conditions		Characteristic Values (per diode) typ.	max.	
I_R	T_{VJ} = 25°C	$V_R = V_{RRM}$		12	mA
	T_{VJ} = 25°C	$V_R = 0.8 \cdot V_{RRM}$		3	mA
	T_{VJ} = 125°C	$V_R = 0.8 \cdot V_{RRM}$		80	mA
V_F	I_F = 150 A;	T_{VJ} = 125°C		1.05	V
		T_{VJ} = 25°C		1.27	V
	I_F = 260 A;	T_{VJ} = 125°C		1.19	V
		T_{VJ} = 25°C		1.36	V
V_{T0}	For power-loss calculations only			0.85	V
r_T				1.34	mΩ
R_{thJH}	DC current			0.228	K/W
R_{thJC}	DC current			0.143	K/W
t_{rr}	I_F = 300 A	T_{VJ} = 100°C	250	300	ns
I_{RM}	V_R = 300 V	T_{VJ} = 25°C		44	A
	-di/dt = 400 A/µs	T_{VJ} = 100°C		66	A

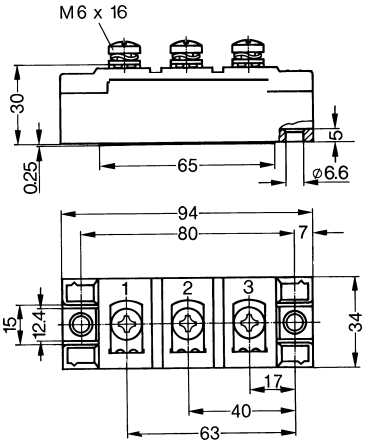
① I_{FAVM} rating includes reverse blocking losses at T_{VJM}, V_R = 0.6 V_{RRM}, duty cycle d = 0.5
Data according to IEC 60747
IXYS reserves the right to change limits, test conditions and dimensions

Features
- International standard package with DCB ceramic base plate
- Planar passivated chips
- Short recovery time
- Low switching losses
- Soft recovery behaviour
- Isolation voltage 3600 V~
- UL registered E 72873

Applications
- Antiparallel diode for high frequency switching devices
- Free wheeling diode in converters and motor control circuits
- Inductive heating and melting
- Uninterruptible power supplies (UPS)
- Ultrasonic cleaners and welders

Advantages
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

Dimensions in mm (1 mm = 0.0394")



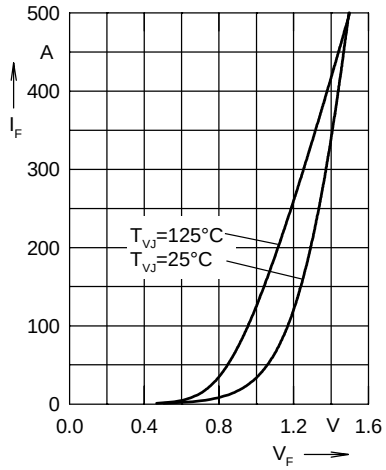


Fig. 1 Forward current I_F versus max. voltage drop V_F per leg

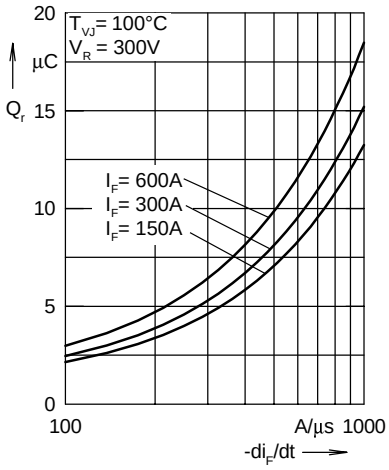


Fig. 2 Typ. reverse recovery charge Q_r versus $-di_F/dt$

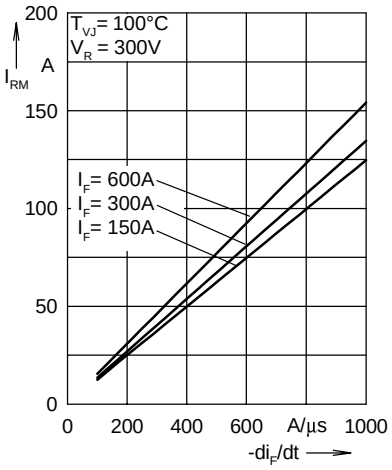


Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

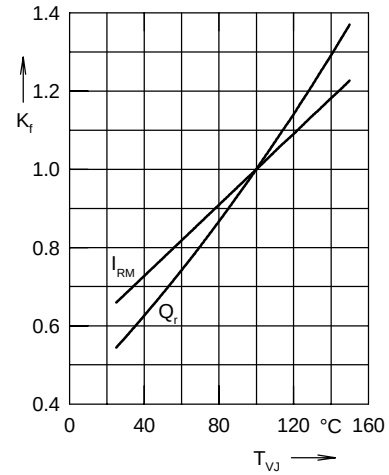


Fig. 4 Dynamic parameters Q_r, I_{RM} versus junction temperature T_{VJ}

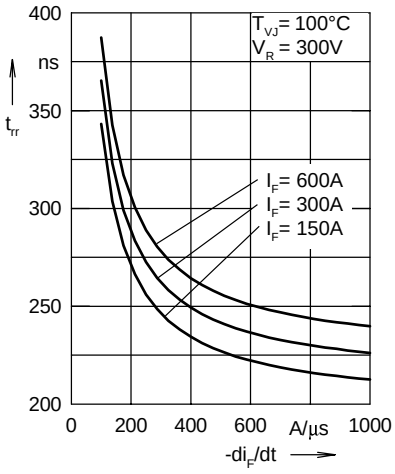


Fig. 5 Typ. recovery time t_{rr} versus $-di_F/dt$

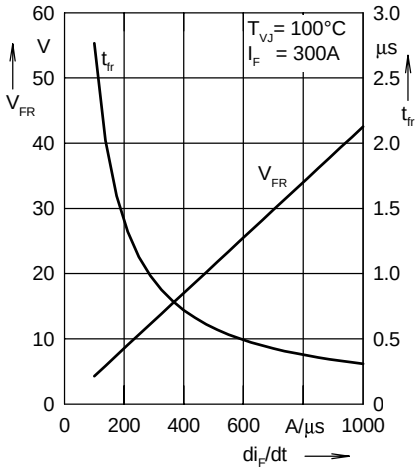


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_F/dt

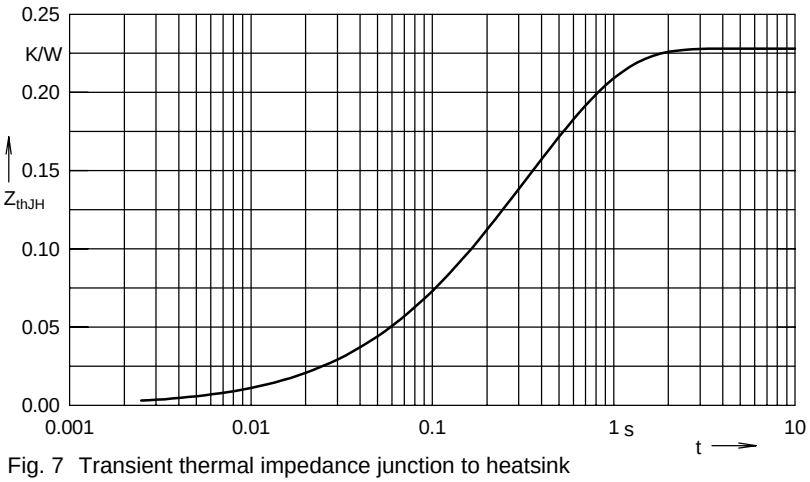


Fig. 7 Transient thermal impedance junction to heatsink

Constants for Z_{thJS} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.002	0.08
2	0.008	0.024
3	0.054	0.112
4	0.164	0.464

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